Texas Instruments Inc. (DUNS# 00-732-1904) Supplier Name:

Contact Info:

ti.com/support
Distribute - RoHS and IEC 62474 DB Form/Declaration Type:

08/26/2022

Details for "MAX3243EIRHBR"

Current Product Information

Ti part number	Lead finish/Ball material	MSL rating/peak reflow	Assembly site	Package Pins	Package body size (mm)	Total device mass (mg)*
MAX3243EIRHBR	NIPDAU	Level-2-260C-1 YFAR	TI MAI AYSIA A/T	RHB 32	5.0x5.0x0.9	67.8

The summary mass is a rounded value and will be within approximately +/- 10% of the detailed mass value.

Environmental Ratings Information

RoHS	REACH	Green	IEC 62474 DB	
Yes	Yes	Yes	Yes	

Component Information

				Homoge	neous Material Level	Component Level	
Component	Substance	CAS Number	Amount (mg)	Percentage %	ppm	Percentage %	ppm
Bond Wire							
Copper and Its Alloys	Copper	7440-50-8	0.13028	99.997697	999977	0.192036	1920
Copper and Its Alloys	Iron	7439-89-6	0.000001	0.000768	8	0.000001	0
Precious Metals	Silver	7440-22-4	0.000002	0.001535	15	0.000003	0
Sub-Total			0.130283	100	1000000	0.19204	1920
Die Attach Adhesive							
Other Inorganic Materials	Silica	7631-86-9	0.030331	2.000028	20000	0.044709	447
Precious Metals	Silver	7440-22-4	1.046405	68.999999	690000	1.542425	15424
Thermoplastics	Ероху	85954-11-6	0.439793	28.999973	290000	0.648265	6483
Sub-Total			1.516529	100	1000000	2.235398	22354
Lead Frame							
Copper and Its Alloys	Copper	7440-50-8	29.923875	99.25	992500	44.108465	441085
Other Nonferrous Metals and Alloys	Chromium	7440-47-3	0.07839	0.26	2600	0.115549	1155
Other Nonferrous Metals and Alloys	Tin	7440-31-5	0.075375	0.25	2500	0.111104	1111
Zinc and Its Alloys	Zinc	7440-66-6	0.07236	0.24	2400	0.10666	1067
Sub-Total			30.15	100	1000000	44.441778	444418
Lead Frame Plating							
Nickel and Its Alloys	Nickel	7440-02-0	0.516502	95.120074	951201	0.761336	7613
Precious Metals	Gold	7440-57-5	0.004235	0.779926	7799	0.006242	62
Precious Metals	Palladium	7440-05-3	0.022263	4.1	41000	0.032816	328
Sub-Total			0.543	100	1000000	0.800394	8004
Mold Compound							
Other Inorganic Materials	Fused Silica	60676-86-0	27.63723	90.499999	905000	40.737899	407379
Other Plastics and Rubber	Carbon Black	1333-86-4	0.152692	0.5	5000	0.225071	2251
Thermoplastics	Ероху	85954-11-6	2.748454	9.000001	90000	4.051283	40513
Sub-Total			30.538376	100	1000000	45.014253	450143
Semiconductor Device							
Ceramics / Glass	Doped Silicon	7440-21-3	4.963382	100	1000000	7.316137	73161
Sub-Total			4.963382	100	1000000	7.316137	73161
Total			67.84157		_	100	1000000

Important Note

The ppm calculations are at the homogeneous material level and are maximum concentration values. The ppm displayed represents the homogeneous material with the highest ppm

for that substance. The amount (mg) calculations represent the maximum total amount of each substance within the component.

The ppm calculations are at the component level and are average concentration values. The amount (mg) calculations represent the average total amount of each substance within the component. See Glossary of Terms for more details.

There is a remote possibility the Customer Part Number (CPN) your company uses could reference more than one TI part number. This is due to two or more users (EMSis or subcontractors) using the same CPN for different TI part numbers. If this occurs, please check your Customer Part Number and cross reference it with the TI part number seen on this page.

For an explanation of the methods used to determine material weights, See Product Content Methodology

Material Declaration Certificate for Semiconductor IC Packaged Products

TI certifies that the material content information provided by TI is representative and accurate to the best of their knowledge based on material information provided by its suppliers and their combination into finished IC packaged products. TI semiconductor products designated to be "Pb-free", "Green" or "RoHS Exempt" fully meets the latest EU RoHS Directive requirements along with other legislation as seen in the former JIG-101 list that has been transferred to the IEC 62474 database.

TI bases its material content information on information provided by third-party suppliers and has taken, and continues to take, reasonably diligent steps to provide any required or available information. TI may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. Tl and Tl suppliers may consider certain information to be proprietary, and thus certain information may not be available for release by Tl. The material content information is provided by Tl "as is."

For additional information, please contact TI customer support.

Signature: (click here for a fuller statement with a signed certificate)

Name/Title: Hubie Payne, Vice President, Worldwide SC Quality For further environmental statements, please go to www.ti.com/ecoinfo Created on: 08/26/2022

ROHS: Means TI semiconductor products that are compliant with the current RoHS requirement that the maximum concentration values of the ten substances listed in RoHS Annex II do not exceed 0.1 % by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI semiconductor products labeled as "RoHS Compliant" are suitable for use in specified lead-free processes. TI may also reference these types of semiconductor products as "Pb-Free." These TI semiconductor products are also fully compliant with GADSL and the IEC 62474 database for electronic requirements.

RoHS Exempt: Means TI semiconductor products that contain lead (Pb) above the RoHS Annex II threshold, but that fall within one of the specific RoHS exemptions noted above or documented in http://www.ti.com/lit/pdf/szzq088

Green: Means the content of Chlorine (CI) and Bromine (Br)-based flame retardants meet JS709B low halogen requirements of <=1 000ppm threshold; Antimony trioxide (Sb203) contained in halogen based flame retardant materials meets the <=1 000ppm threshold requirement; and Beryllium Oxide (BeO) is <=1000ppm.